

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-36. (Canceled)

37. (Original) A clad board for forming circuitry, being manufactured through:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

said clad board comprising:

a fiber sheet included in the pre-preg sheet;

resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion; and

a resin layer formed smoothly on the fiber sheet, the resin layer being made of material identical to the resin material.

38-39. (Canceled)

40. (Currently Amended) ~~A~~The clad board for forming circuitry, being manufactured through: of claim 37,

~~sticking a releasing film to a pre-preg sheet;~~

~~forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through hole and a through hole;~~

~~filling the hole with conductive paste;~~

~~peeling off the releasing film; and~~

~~heating and pressing a metal foil onto the pre-preg sheet,~~

~~said board comprising:~~

~~awherein the fiber sheet included in the pre-preg sheet, having has a density ranging from 700kg/m³ to 1000kg/m³; and~~

~~resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.~~

41. (Currently Amended) ~~A~~The clad board for forming circuitry, being manufactured through:of claim 37,

~~sticking a releasing film to a pre-preg sheet;~~

~~forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through hole and a through hole;~~

~~filling the hole with conductive paste;~~

~~peeling off the releasing film; and~~

~~heating and pressing a metal foil onto the pre-preg sheet,~~

~~said board comprising:~~

~~awherein the fiber sheet included in the pre-preg sheet~~includes;

~~a first layer included in the fiber sheet and disposed at a surface of the fiber sheet; and~~

~~a second layer included in the fiber sheet, the second layer having a density lower than a density of the first layer; and~~

~~resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.~~

42-43. (Canceled)

44. (Currently Amended) ~~A~~The clad board for forming circuitry, being manufactured through ~~of claim 37,~~

~~sticking a releasing film to a pre-preg sheet;~~

~~forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through hole and a through hole;~~

~~filling the hole with conductive paste;~~

~~peeling off the releasing film; and~~

~~heating and pressing a metal foil onto the pre-preg sheet,~~

~~said board comprising:~~

~~a~~wherein the fiber sheet included in the pre-preg sheet ~~includes;~~

~~a first layer included in said fiber sheet; and~~

~~a second layer included in said fiber sheet, the second layer having a density different from a density of the first layer; and~~

~~resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.~~

45-46. (Canceled)

47. (Currently Amended) ~~A~~The clad board for forming circuitry, being manufactured through ~~of claim 37,~~

~~sticking a releasing film to a pre-preg sheet;~~

~~forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through hole and a through hole;~~

~~filling the hole with conductive paste;~~

~~peeling off the releasing film; and~~

~~heating and pressing a metal foil onto the pre-preg sheet,~~

~~said board comprising:~~

~~a-wherein the fiber sheet included in the pre-preg sheet includes;~~

~~first and second layers included in the fiber sheet, being disposed on at respective surfaces of the fiber sheet; and~~

~~a third layer included in the fiber sheet, being located between the first and second layers, the third layer having a density lower than respective densities of the first and second layers; and~~

~~resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.~~

48-58. (Canceled)

59. (Currently Amended) ~~A~~The clad board for forming circuitry, being manufactured through of claim 37,

~~sticking a releasing film to a pre-preg sheet;~~

~~forming a hole in the pre-preg sheet including the releasing film, the hole being one of a non-through hole and a through hole;~~

~~filling the hole with conductive paste;~~

~~peeling off the releasing film; and~~

~~heating and pressing a metal foil onto the pre-preg sheet,~~

~~said clad board comprising:~~

~~wherein the fiber sheet has a hole formed therein, said clad board further comprising a
conductive paste filling the hole of the fiber sheet, the conductive paste including a conductive
particle included in the conductive paste, being shaped in non-spherical.~~

60-65. (Canceled)

66. (Original) A core board for a clad board for forming circuitry, comprising:

a fiber sheet;

resin material impregnated into the fiber sheet, the resin material including at least one
of thermoplastic resin and thermosetting resin having semi-cured portion; and

a resin layer formed on the fiber sheet, being made of material identical to the resin
material.

67-68. (Canceled)

69. (Currently Amended) ~~A~~The core board ~~for a clad board for forming circuitry,~~
~~comprising:~~of claim 66,

~~a~~wherein the fiber sheet ~~having~~has a density ranging from 700kg/m^3 to 1000kg/m^3 ; ~~and~~

~~resin material impregnated into the fiber sheet, the resin material including at least one
of thermoplastic resin and thermosetting resin having semi-cured portion.~~

70. (Currently Amended) ~~A~~The core board ~~for a clad board for forming circuitry,~~
~~comprising:~~of claim 66,

~~a~~wherein the fiber sheet includes;

~~a first layer included in the fiber sheet and disposed at a surface of the fiber sheet; and~~

~~a second layer included in the fiber sheet, having a density lower than a density of the
first layer; and~~

~~resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.~~

71-72. (Canceled)

73. (Currently Amended) ~~A~~The core board for a clad board for forming circuitry, comprising: of claim 66,

awherein the fiber sheet includes;

a first layer included in the fiber sheet; and

a second layer included in the fiber sheet, having a density different from a density of the first layer; and

~~resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.~~

74-75. (Canceled)

76. (Currently Amended) ~~A~~The core board for a clad board for forming circuitry, comprising: of claim 66,

awherein the fiber sheet includes;

first and second layers included in the fiber sheet, being disposed on at respective outermost sides of the fiber sheet; and

a third layer included in said fiber sheet, being located between the first and second layers, having a density lower than respective densities of the first and second layers; and

~~resin material impregnated into the fiber sheet, the resin material including at least one of thermoplastic resin and thermosetting resin having semi-cured portion.~~

77-82. (Canceled)